

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC123A

Dual Retriggerable Monostable Multivibrators (with Clear)



ADE-205-438 (Z)
1st. Edition
Sep. 2000

Description

This multivibrator features both a negative, A, and a positive, B, transition triggered input, either of which can be used as an inhibit input. Also included is a clear input that when taken low resets the one shot. The HD74HC123A can be triggered on the positive transition of the clear while A is held low and B is held high.

The HD74HC123A is retriggerable. That is it may be triggered repeatedly while their outputs are generating a pulse and the pulse will be extended.

Pulse width stability over a wide range of temperature. The output pulse equation is simply: $t_w = (R_{ext})(C_{ext})$.

Features

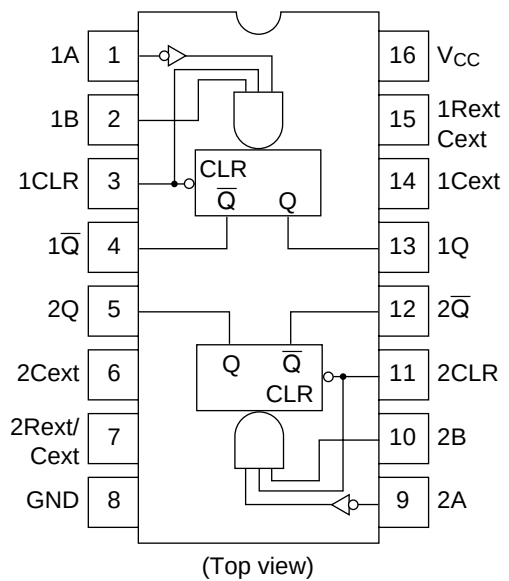
- High Speed Operation
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μA max
- Low Quiescent Supply Current

Function Table

Inputs			Outputs	
Clear	A	B	Q	$\bar{Q}$
L	X	X	L	H
X	H	X	L	H
X	X	L	L	H
H	L			
H		H		
	L	H		

Note: External timing capacitance connects between Cext and Rext/Cext.

Pin Arrangement



DC Characteristics

		Sym- bol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions		
				Min	Typ	Max	Min	Max				
Input voltage		V _{IH}	2.0	1.5	—	—	1.5	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA		
			4.5	3.15	—	—	3.15	—				
			6.0	4.2	—	—	4.2	—				
		V _{IL}	2.0	—	—	0.5	—	0.5	V			
			4.5	—	—	1.35	—	1.35				
			6.0	—	—	1.8	—	1.8				
Output voltage		V _{OH}	2.0	1.9	2.0	—	1.9	—	V		I _{OH} = -4 mA	
			4.5	4.4	4.5	—	4.4	—				
			6.0	5.9	6.0	—	5.9	—				
			4.5	4.18	—	—	4.13	—				
			6.0	5.68	—	—	5.63	—				
		V _{OL}	2.0	—	0.0	0.1	—	0.1	V	I _{OL} = 20 μA		
			4.5	—	0.0	0.1	—	0.1				
			6.0	—	0.0	0.1	—	0.1				
			4.5	—	—	0.26	—	0.33				
			6.0	—	—	0.26	—	0.33				
Input current		I _{in}	6.0	—	—	±0.1	—	±1.0	μA		Vin = V _{CC} or GND	
Quiescent	Standby state	I _{CC}	6.0	—	—	130	—	220	μA		Vin = V _{CC} or	I _{out} = 0 μA
supply current	Active state			—	—	130	—	220	GND		Rext/Cext = 0.5 V _{CC}	

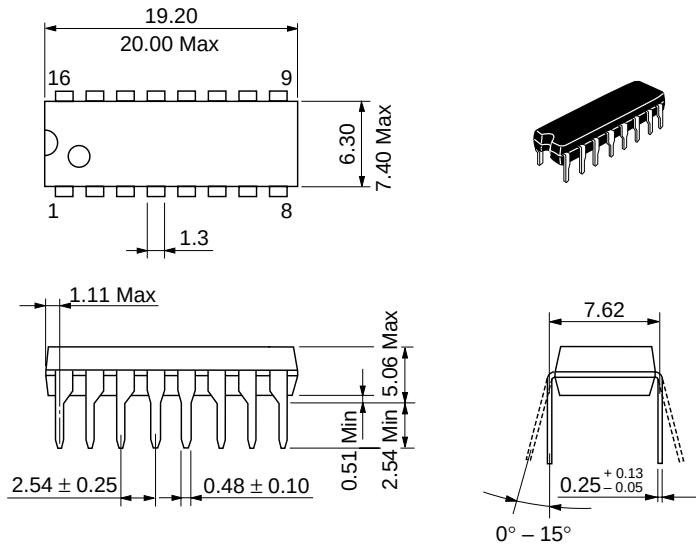
AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = −40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min				Max
Propagation delay time	t _{PLH}	2.0	—	—	210	—	265	ns	A, B or Clear to Q	
		4.5	—	22	42	—	53			
		6.0	—	—	36	—	45			
	t _{PHL}	2.0	—	—	240	—	300	ns	A, B or Clear to $\overline{Q}$	
		4.5	—	23	48	—	60			
		6.0	—	—	41	—	51			
	t _{PHL}	2.0	—	—	170	—	215	ns	Clear to Q	
		4.5	—	18	34	—	43			
		6.0	—	—	29	—	37			
	t _{PLH}	2.0	—	—	180	—	225	ns	Clear to $\overline{Q}$	
		4.5	—	16	36	—	45			
		6.0	—	—	31	—	38			
Output rise time	t _{TLH}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Output fall time	t _{THL}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Pulse width	t _w	2.0	150	—	—	190	—	ns	A, B, Clear	
		4.5	30	6	—	38	—			
		6.0	26	—	—	33	—			
Minimum output pulse width	t _{WQ(min)}	2.0	—	1.5	—	—	—	μs	Cext = 28 pF	Rext = 6 kΩ
		4.5	—	450	—	—	—	ns		Rext = 2 kΩ
		6.0	—	380	—	—	—			
Output pulse width	t _{WQ}	4.5	—	1.0	—	—	—	ms	Cext = 0.1 μF, Rext = 10 kΩ	
Input capacitance	Cin	—	—	5	10	—	10	pF		

Caution in use: In order to prevent any malfunctions due to noise, connect a high-frequency performance capacitor between V_{CC} and GND, and keep the wiring between the External components and Cext, Rext/Cext pins as short as possible.

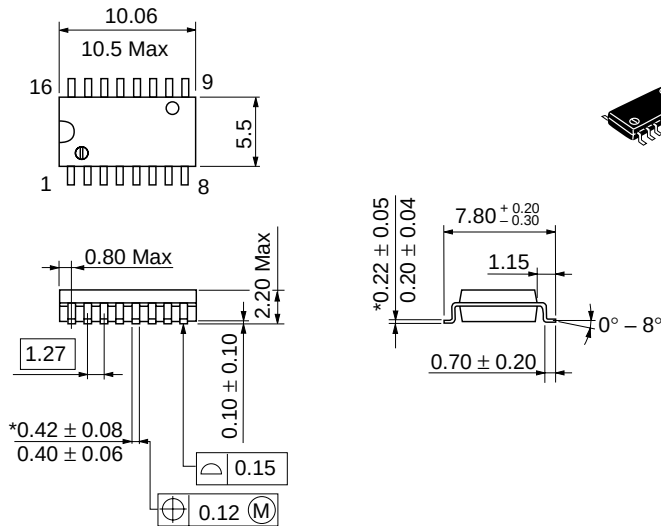
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica	:	http://semiconductor.hitachi.com/
	Europe	:	http://www.hitachi-eu.com/hel/ecg
	Asia	:	http://sicapac.hitachi-asia.com
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For further information write to:Hitachi Semiconductor
(America) Inc.179 East Tasman Drive,
San Jose, CA 95134

Tel: <1> (408) 433-1990

Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic Components Group

Dornacher Straße 3

D-85622 Feldkirchen, Munich

Germany

Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.

Electronic Components Group.

Whitebrook Park

Lower Cookham Road

Maidenhead

Berkshire SL6 8YA, United Kingdom

Tel: <44> (1628) 585000

Fax: <44> (1628) 585160

Hitachi Asia Ltd.

Hitachi Tower

16 Collyer Quay #20-00,

Singapore 049318

Tel: <65>-538-6533/538-8577

Fax: <65>-538-6933/538-3877

URL: <http://www.hitachi.com.sg>

Hitachi Asia Ltd.

(Taipei Branch Office)

4/F, No. 167, Tun Hwa North Road,

Hung-Kuo Building,

Taipei (105), Taiwan

Tel: <886>-(2)-2718-3666

Fax: <886>-(2)-2718-8180

Telex: 23222 HAS-TP

URL: <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.

Group III (Electronic Components)

7/F., North Tower,

World Finance Centre,

Harbour City, Canton Road

Tsim Sha Tsui, Kowloon,

Hong Kong

Tel: <852>-(2)-735-9218

Fax: <852>-(2)-730-0281

URL: <http://www.hitachi.com.hk>